5V TTL to Differential ECL Translator

The MC10ELT/100ELT24 is a TTL to differential ECL translator. Because ECL levels are used a +5 V, -5.2 V (or -4.5 V) and ground are required. The small outline 8–lead package and the single gate of the ELT24 makes it ideal for those applications where space, performance and low power are at a premium.

The 100 Series contains temperature compensation.

- 0.8 ns t_{PHL}, 0.95 ns t_{PLH} Typical Propagation Delay
- PNP TTL Inputs for Minimal Loading
- Flow Through Pinouts
- Operating Range: $V_{CC} = 4.5 \text{ V}$ to 5.5 V; $V_{EE} = -4.2 \text{ V}$ to -5.5 V with GND = 0 V
- Pb-Free Packages are Available



http://onsemi.com

MARKING DIAGRAMS*



SO-8 D SUFFIX CASE 751











 $\begin{array}{lll} H = MC10 & L = Wafer Lot \\ K = MC100 & Y = Year \\ A = Assembly Location & W = Work Week \end{array}$

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

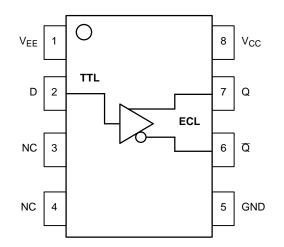


Table 1. PIN DESCRIPTION

Pin	Function					
Q, \overline{Q}	ECL Differential Outputs*					
D	TTL Input					
V _{CC}	Positive Supply					
V _{EE}	Negative Supply					
GND	Ground					
NC	No Connect					

^{*}Output state undetermined when inputs are open.

Figure 1. Logic Diagram and Pinout Assignment

Table 2. ATTRIBUTES

Characteris	Value					
Internal Input Pulldown Resistor	N/A					
Internal Input Pullup Resistor	N/A					
ESD Protection	Human Body Model Machine Model	> 4 kV > 200 V				
Moisture Sensitivity, Indefinite Tim	e Out of Drypack (Note 1)	Level 1				
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in				
Transistor Count		51				
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test						

^{1.} For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	GND = 0 V	$V_{EE} = -5.0 \text{ V}$	7	V
V _{EE}	Negative Power Supply	GND = 0 V	V _{CC} = +5.0 V	-8	V
V _{IN}	Input Voltage	GND = 0 V	$V_{I} \leq V_{CC}$	0 to V _{CC}	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SO-8 SO-8	190 130	°C/W °C/W
θJC	Thermal Resistance (Junction-to-Case)	Standard Board	SO-8	41 to 44	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W °C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 ±5%	°C/W
T _{sol}	Wave Solder	< 2 to 3 sec @ 248°C		265	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 4. 10ELT SERIES NECL OUTPUT DC CHARACTERISTICS $V_{CC} = 5.0 \text{ V}$; $V_{EE} = -5.0 \text{ V}$; GND = 0 V (Note 2)

			-40°C 25°C		85°C						
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{CC}	V _{CC} Power Supply Current			7.0		4.5	7.0			7.0	mA
I _{EE}	Power Supply Current			18		12.5	18			18	mA
V _{OH}	Output HIGH Voltage (Note 3)	-1080	-990	-890	-980	-895	-810	-910	-815	-720	mV
V _{OL}	Output LOW Voltage (Note 3)	-1950	-1800	-1650	-1950	-1790	-1630	-1950	-1773	-1595	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Output parameters vary 1:1 with GND. V_{CC} can vary 4.5 V / 5.5 V. V_{EE} can vary -4.2 V / -5.5 V.
- 3. Outputs are terminated through a 50 Ω resistor to GND 2 V.

Table 5. 100ELT SERIES NECL OUTPUT DC CHARACTERISTICS $V_{CC} = 5.0 \text{ V}$; $V_{EE} = -5.0 \text{ V}$; GND = 0 V (Note 4)

		-40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Icc	V _{CC} Power Supply Current			7.0		4.5	7.0			7.0	mA
I _{EE}	Power Supply Current			18		12.5	18			18	mA
V _{OH}	Output HIGH Voltage (Note 5)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V _{OL}	Output LOW Voltage (Note 5)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 4. Output parameters vary 1:1 with GND. V_{CC} can vary 4.5 V / 5.5 V. V_{EE} can vary -4.2 V / -5.5 V.
- 5. Outputs are terminated through a 50 Ω resistor to GND 2 V.

Table 6. TTL INPUT DC CHARACTERISTICS $V_{CC} = 4.5 \text{ V}$ to 5.5 V; $V_{EE} = -4.2 \text{ V}$ to -5.5 V; GND = 0.0 V; $T_A = -40 ^{\circ}\text{C}$ to $+85 ^{\circ}\text{C}$

Symbol	Characteristic	Condition	Min	Тур	Max	Unit
I _{IH}	Input HIGH Current	V _{IN} = 2.7 V			20	μΑ
I _{IHH}	Input HIGH Current	V _{IN} = 7.0 V			100	μΑ
I _{IL}	Input LOW Current	V _{IN} = 0.5 V			-0.6	mA
V _{IK}	Input Clamp Diode Voltage	I _{IN} = -18 mA			-1.2	V
V _{IH}	Input HIGH Voltage		2.0			V
V _{IL}	Input LOW Voltage				0.8	V

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 7. AC CHARACTERISTICS $V_{CC} = 4.5 \text{ V}$ to 5.5 V; $V_{EE} = -4.2 \text{ V}$ to -5.5 V; GND = 0.0 V

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency					400					MHz
t _{PLH}	Propagation Delay (Note 6) 1.5 V to 50%	0.5		2.0	0.5	0.95	2.0	0.5		2.0	ns
t _{PHL}	Propagation Delay (Note 6) 1.5 V to 50%	0.5		2.0	0.5	0.8	2.0	0.5		2.0	ns
t _{JITTER}	Random Clock Jitter (RMS)					2.5					ps
t _r /t _f	Output Rise/Fall Time (20–80%)	0.25		1.25	0.25		1.25	0.25		1.25	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 6. Specifications for standard TTL input signal.
- 7. Devices are designed to meet the AC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

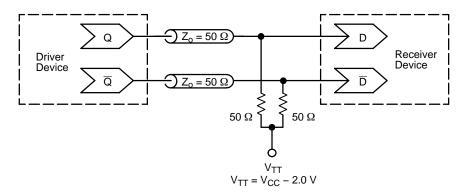


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10ELT24D	SOIC-8	98 Units / Rail
MC10ELT24DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC10ELT24DR2	SOIC-8	2500 / Tape & Reel
MC10ELT24DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC10ELT24DT	TSSOP-2	100 Units / Rail
MC10ELT24DTR2	TR2 TSSOP-2 2500 / Tape & Reel	
MC10ELT24DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100ELT24D	SOIC-8	98 Units / Rail
MC100ELT24DR2	SOIC-8	2500 / Tape & Reel
MC100ELT24DT	TSSOP-8	100 Units / Rail
MC100ELT24DTR2	TSSOP-8	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1642/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

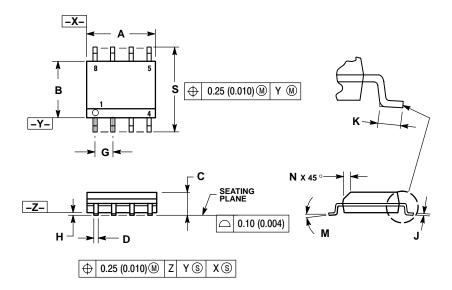
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB **D SUFFIX** CASE 751-07 **ISSUE AC**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

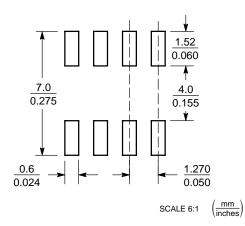
 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) DED SIDE
- MAXIMUM MOLD PROTRUSION 0.15 (0.006)
 PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW
- STANDARD IS 751-07.

	MILLIN	IETERS	INCHES			
DIM	MIN	MIN MAX MIN				
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
O	1.35	1.35 1.75 0.053		0.069		
D	0.33	0.51	0.013	0.020		
G	1.27	7 BSC	0.050 BSC			
Н	0.10	0.25	0.004	0.010		
ſ	0.19	0.25	0.007	0.010		
K	0.40	1.27	0.016	0.050		
М	1 0° 8°		0 °	8 °		
N	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228	0 244		

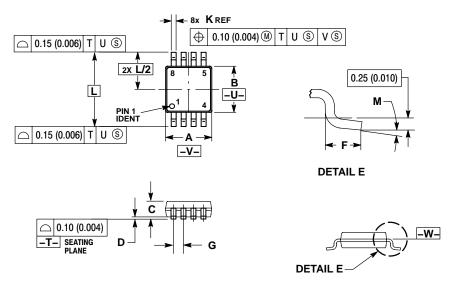
SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



- NOTES:
 1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETER.
- 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	2.90	3.10	0.114	0.122		
В	2.90	3.10	0.114	0.122		
C	0.80	1.10	0.031	0.043		
D	0.05	0.15	0.002	0.006		
F	0.40	0.70	0.016	0.028		
G	0.65	BSC	0.026	BSC		
K	0.25	0.40	0.010	0.016		
L	4.90	BSC	0.193 BSC			
М	0°	6 °	0°	6°		

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